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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant : Baklanov, et al.) Group Art Unit 2814
Appl. No. : 09/844,959)
Filed : April 27, 2001) I hereby certify that this correspondence and all
For : FLUORINATED HARD MASK) marked attachments are being deposited with the
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Examiner : Trinh, H.) and Trademark Office, P.O. Box 2327,
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AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed February 27, 2002 Applicants respectfully request that the Examiner enter the following amendments and consider the following remarks.

IN THE CLAIMS:

Please amend Claims 1-10 as follows:

A1

1. (Amended) A method for forming a patterned hard mask layer in an organic polymer film for an interconnect structure in an integrated circuit, said method comprising:
 fluorinating a part of an organic polymer film, thereby forming a fluorinated part,
 said fluorinated part forming a first hard mask layer;
 forming a patterned second hard mask layer on said film;
 patterning said first hard mask layer using said patterned second hard mask layer as a mask, thereby forming a patterned first hard mask layer;